



Evaluation kit to experiment with different system configurations of XENSIV digital MEMS microphones, using the A<sup>2</sup>B interface in combination with the AURIX microcontroller

### **About this document**

### **Scope and purpose**

This user guide describes the usage and basic operation of the A<sup>2</sup>B evaluation kit. It describes the parts of the kit and includes schematic and pinout of the individual boards.

#### Intended audience

Hardware and software engineers, evaluating Infineon digital XENSIV™ MEMS microphones.

#### **Evaluation kit**

This evaluation kit allows multi microphone audio readout and processing for many applications (e.g. siren detection, beam forming, in-cabin-communication, active noise cancellation, ...). It can be used by customers to develop their own algorithms and experiment with different numbers of microphones in different locations inside or outside of the car. With its magnetic microphone slave modules, it allows easy mounting on any metal surface.

The microphone slave modules are equipped with protective membranes in front of the microphone sound ports and silicon gaskets on the cable feed throughs. This allows real driving test and the data collection even under dusty and slightly wet conditions.

It also shows how to connect the Infineon digital XENSIV™ MEMS microphones to an A<sup>2</sup>B transceiver and how to interface to the AURIX™ microcontroller.

Note: PCB and auxiliary circuits are NOT optimized for final customer design.



A<sup>2</sup>B evaluation kit with the ECU master unit and 4 microphone slave modules.

### Infineon A<sup>2</sup>B evaluation kit



#### **Important notice**

### **Important notice**

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### **Safety precautions**

### **Safety precautions**

Note: Please note the following warnings regarding the hazards associated with development systems.

### Table 1Safety precautions



**Caution:** The evaluation or reference board contains parts and assemblies sensitive to electrostatic discharge (ESD). Electrostatic control precautions are required when installing, testing, servicing or repairing the assembly. Component damage may result if ESD control procedures are not followed. If you are not familiar with electrostatic control procedures, refer to the applicable ESD protection handbooks and guidelines.



**Caution:** The evaluation or reference board is shipped with packing materials that need to be removed prior to installation. Failure to remove all packing materials that are unnecessary for system installation may result in overheating or abnormal operating conditions.

# Infineon A<sup>2</sup>B evaluation kit



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#### The evaluation kit at a glance 1

This evaluation kit is designed for customers who want to develop their own algorithms for sound detection and experiment with different numbers of microphones in different locations inside or outside of the car.

It consists of an ECU master unit with an AURIX™ microcontroller and several microphone slave modules with 4 MEMS microphones each. The audio data from the microphones are transmitted via A<sup>2</sup>B bus to the AURIX™. The system can be configured, how many slave modules and which and how many microphones per slave shall be used. The audio data of up to 8 microphones can be processed inside the AURIX™.

The user can then implement his own algorithm for processing the audio data on the microcontroller.

For easy start and simple demonstration, the AURIX™ is pre-flashed with some simple demo code. Details can be found in chapter 4.2.

#### Main features 1.1

- Full evaluation kit for multi microphone audio readout and processing for many different applications
- Target applications: Siren detection, hands-free speech, voice commands, beam-forming, in-cabincommunication, active noise cancellation (ANC), ...
- System can be used for driving tests outside on a demo car
- Phantom powered slave modules with 4 microphones each
- Slave PCB mounted in a spray water sealed housing
- Mountable to the outside of a car by magnets
- Aerodynamic shape to avoid audible air turbulences
- AURIX<sup>™</sup> sample code with up to 8 TDM channels
- Predefined configurations available

User guide

- 4 slaves with 2 active microphones each
- 2 slaves with 4 active microphones each
- 1 slave with 4 active microphones
- Individual configuration via SigmaStudio possible

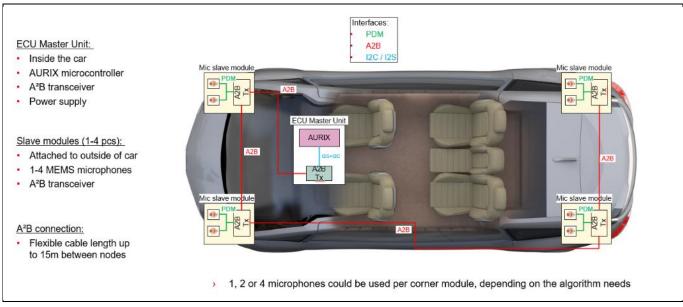


Figure 1

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## 1.2 Scope of supply

The kit consists of a master unit and a variable number of slaves, cables and housings, which also can be ordered separately.

- 1. ECU master unit:
  - a. Base microcontroller board
  - b. A<sup>2</sup>B master board
  - c. Microphone array extension with 15 LEDs
- 2. Housing for the ECU master unit
- 3. Power supply 12V
- 4. 1...4 slave modules, equipped with 4 MEMS microphones IM67D130A each
- 5. Magnetic housing for the slave board
- 6. Cables with different length to interconnect the master and the slaves

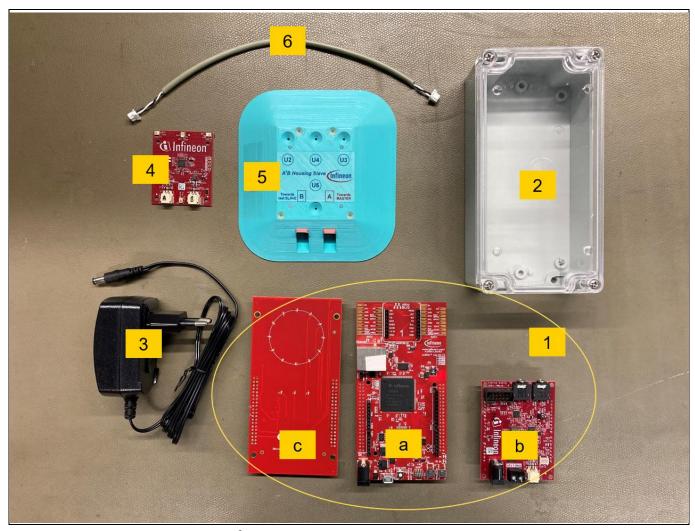


Figure 2 Components of the A<sup>2</sup>B Evaluation Kit

## Infineon A<sup>2</sup>B evaluation kit

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Table 2Order information

Name	Item	Description	Order code	
EVAL_A2B_Kit-Full	1x AURIX™ Lite Kit TC375	Complete A <sup>2</sup> B-Kit with all	SP005742620	
	1x A2B_Extension	boards, housings and cables		
	(Mic-Array + A2B Master	included (2 slaves)		
	Board)			
	2x EVAL_A2B_SIM67D130A			
	2x EVAL_A2B_S-Housing			
	1x EVAL_A2B_M-Housing			
	Cables 2x 25cm + 2x 400cm)	1		
AURIX Lite Kit TC375	AURIX™ base board	AURIX <sup>™</sup> Arduino shield as base for the ECU master unit	SP005551747	
EVAL_A2B_Extension	A <sup>2</sup> B master board	Extension for AURIX™ shield to	SP005742622	
		allow A <sup>2</sup> B operation Note: AURIX Lite Kit TC375 and		
		housing not included		
	Microphone array extension	Extension for AURIX™ shield for		
	merophone array excension	display purpose		
	Power supply 12V	Main power supply for the		
	,	whole evaluation kit		
EVAL_A2B_SIM67D130A	1x microphone slave PCB	Slave PCB, equipped with 4	SP005742624	
	1x cable, ~25 cm	MEMS microphones IM67D130A		
		and one cable (housing not included)		
EVAL_A2B_S-Housing	Slave housing only	Magnetic housing for A2B_Slave	SP005742626	
LVAL_AZD_3-Housing	Stave flousing office	with gaskets and membranes	35003742020	
EVAL_A2B_M-Housing	Master housing only	Housing for A2B_Extension	SP005742628	
	indices moderning conf	(ECU master unit)	0.000.12020	
EVAL_A2B_Cable-025	1x cable only	Cable to interconnect the	SP005742630	
	Length: ~25 cm	master and the slaves for bench		
		tests		
EVAL_A2B_Cable-400	1x cable only	Cable to interconnect the	SP005742632	
	Length: ~400 cm	master and the slaves for		
		driving tests		

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## 2 Quick start

The following chapter describes the steps to connect, power-up and start the evaluation kit.

- 1. Connect the ECU master unit A<sup>2</sup>B output to the A<sup>2</sup>B connector "A" of the first slave
- 2. Connect the A<sup>2</sup>B connector "B" of the first slave to the A<sup>2</sup>B connector "A" of the second slave
- 3. Connect all slaves in the same manner ("B" of the previous slave to "A" of the next slave)
- 4. Connect the 12V power supply line to the A<sup>2</sup>B master board (Figure 6)
- 5. Apply power
- 6. Press the "RESET" button on the AURIX™ lite board (Figure 5)
- 7. Now the LED ring indicates the live sound level and an audio mix of all 8 microphones is available on the headphone output of the A<sup>2</sup>B master board. Details can be found in chapter 4.2.

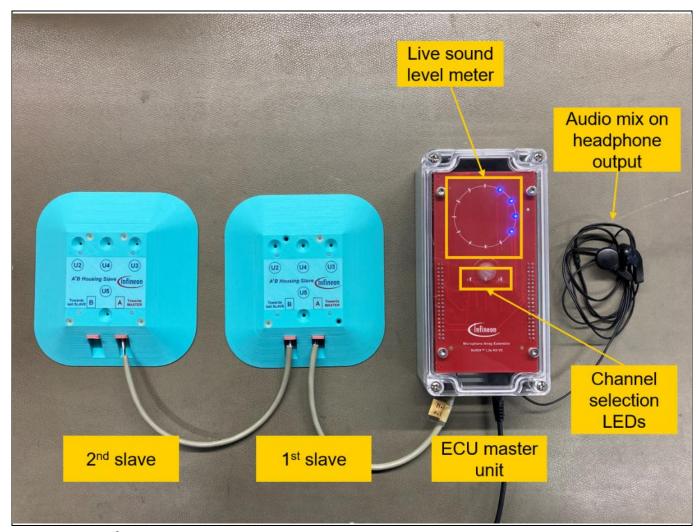


Figure 3 A<sup>2</sup>B evaluation board in operation with demo software

### **Evaluation kit to experiment with different system configurations of XENSIV**



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## 3 System hardware and functional description

The following chapter describes and explains the different components of the evaluation kit.

### 3.1 ECU master unit

The master unit consists of three boards.

- AURIX™ lite kit TC375
- A<sup>2</sup>B master board
- Microphone array extension

For operation, all three boards must be stacked together. The function and operations are described in the chapters below.

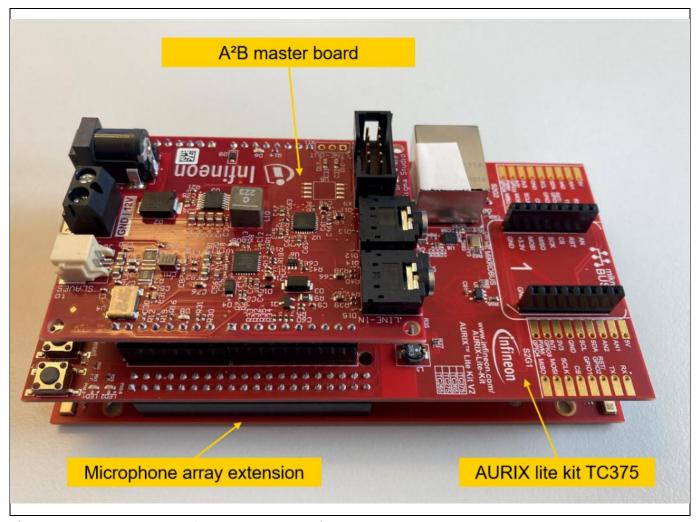


Figure 4 Board stack of the ECU master unit

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## 3.1.1 AURIX™ lite kit

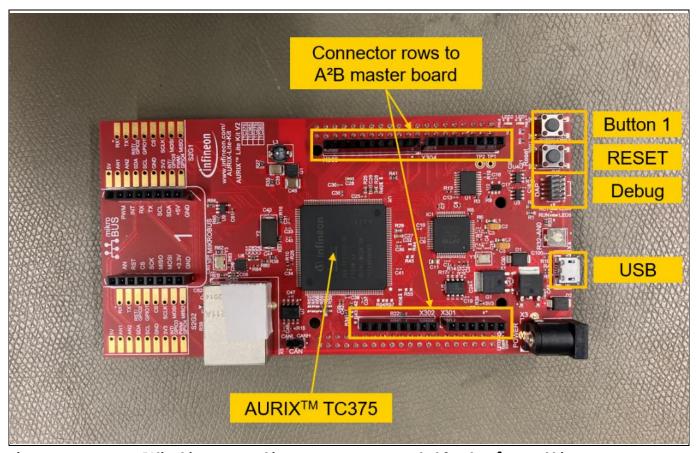


Figure 5 AURIX™ lite kit TC375 and its components as needed for the A²2B eval kit

- RESET:
- o Pressing the reset button will lead to a RESET of the AURIX™.
- Button 1:
  - o Multipurpose input for the AURIX™. Example of usage see chapter 4.2.
- Debug and USB
  - Either of the two connectors can be used for programming and debugging purpose. For details, please refer to [1].

Note: The power connector of the  $AURIX^{TM}$  lite kit must not be used, as the complete kit is powered via the  $A^2B$  master board.

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### 3.1.2 A<sup>2</sup>B master board

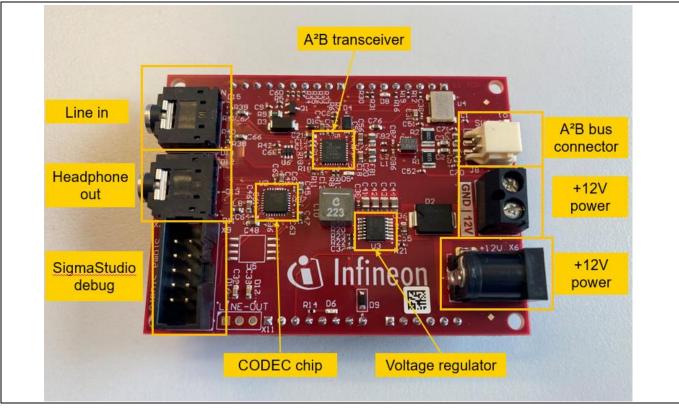


Figure 6 A<sup>2</sup>B master board and its components

The master board consists of the following components:

- +12V power:
  - o Central power connector for the complete evaluation kit
  - The kit can either be powered via the 12V plug and an AC/DC power supply or by connecting the power terminals to a 12V car outlet.
- A<sup>2</sup>B bus connector:
  - 2-pin DuraClik connector (Molex 502352-0200) for the A<sup>2</sup>B bus; compatible to most other A<sup>2</sup>B systems on the market.
- Line-in plug:
  - o Audio input for code evaluation
- Headphone plug:
  - o Audio output for debugging or connection to recording device
- SigmaStudio connector:
  - Debug connection (optional) to allow configuration of the A<sup>2</sup>B transceivers via the SigmaStudio<sup>®</sup> graphical development tool [5].
  - o Transceiver configuration can also be added directly in the source code. Predefined configuration file can be downloaded from the AURIX™ code library on GitHub [3].

A<sup>2</sup>B transceiver: AD2428WCCSZ01 – Analog Devices
 CODEC chip: ADAU1761BCPZ – Analog Devices

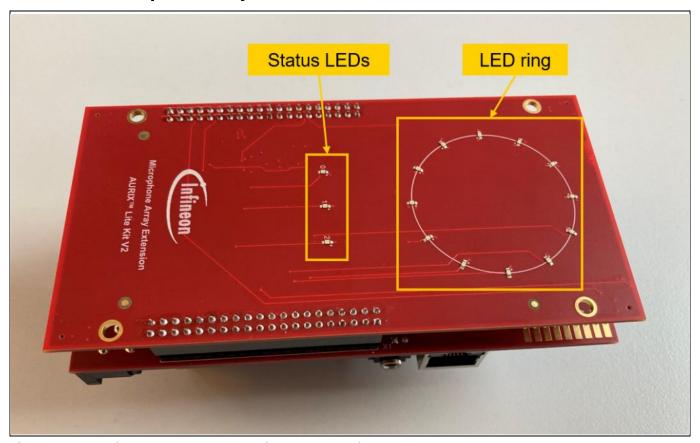
Voltage regulator: TLS4120D0EPV – Infineon OPTIREG™ Step-Down Regulator

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## 3.1.3 Microphone array extension board



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Figure 7 Microphone array extension board and its components

- Status LEDs:
  - Three multipurpose LEDs
  - o Controlled via GPIOs from the AURIX™
- LED ring:
  - o Twelve multipurpose LEDs (e.g. direction detection)
  - o Controlled via GPIOs from the AURIX™

The default function of the different LEDs is described in chapter 4.2.

Details about the board can be found here: [2]

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## 3.2 Microphone slave module

### 3.2.1 Slave PCB

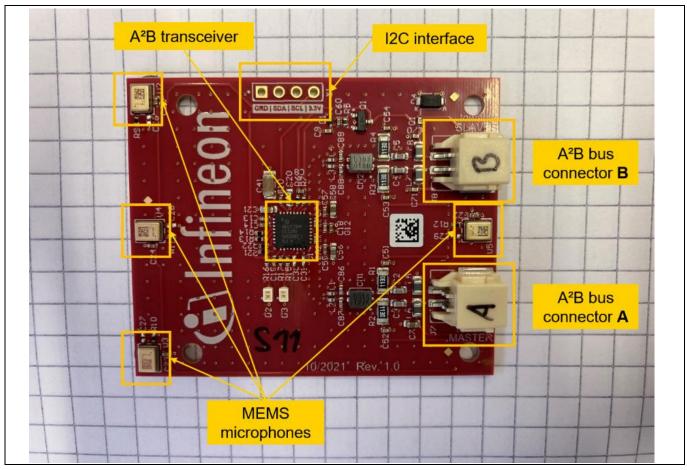


Figure 8 Microphone slave PCB and its components

The microphone slave PCB is equipped with four XENSIV<sup>™</sup> high performance microphones. The A<sup>2</sup>B transceiver can be configured, which microphone channels to transmit to the ECU master unit via the A<sup>2</sup>B bus.

• MEMS microphones: Automotive qualified XENSIV<sup>™</sup> digital MEMS microphones IM67D130A [4]

• A<sup>2</sup>B transceiver: AD2428WCCSZ01 – Analog Devices

A<sup>2</sup>B bus connector:

- o Connector A: connection towards master
- o Connector B: connection towards last slave
- 2-pin DuraClik connector (Molex 502352-0200) for the A<sup>2</sup>B bus; compatible to most other A<sup>2</sup>B systems on the market.
- I2C interface: Optional connection for configuring of the A<sup>2</sup>B transceiver

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## 3.2.2 Slave housing

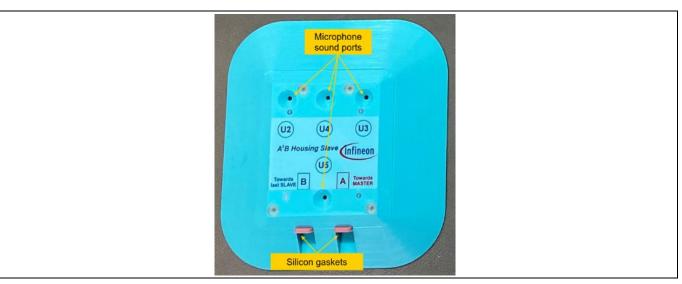


Figure 9 Slave housing

- The magnetic slave housing allows easy mounting to all metal surfaces (e.g. car chassis) due to strong magnets
- Protective membranes under the sound port protects the MEMS microphone from dust and water. See also Figure 10.

Note:

The protective membranes have an influence on the frequency response of the system. They can be removed if needed, but then care must be taken to avoid particles or water to enter the microphone sound port.

- Silicon gaskets around the connection cables to protect for intruding water
- Conical shaped sound ports for the microphones for improved frequency response
- Chamfered side walls to reduce air turbulences during driving tests

Attention: Make sure the metal surface underneath the slave is clean to avoid scratches on the lacquer when mounting on a test car.

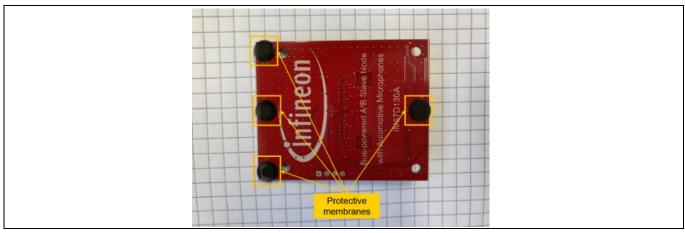


Figure 10 Protective membranes on the backside of the slave PCB

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## 3.3 Cables



Cables to interconnect the master and the slaves can be ordered in different length. See also order information in Table 2.

The cables are equipped with the 2-pin DuraClik connectors (Molex 502351-0200).

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### 4 Software

### 4.1 General info

- The PDM data from the digital MEMS microphones is filtered into a PCM audio signal on the A<sup>2</sup>B transceiver. The audio data are then transferred to the ECU master unit via the A<sup>2</sup>B bus.
- The transceiver on the master board sends the data in an 8 channel TDM stream to the AURIX™.
- Here, they are stored in 8 different buffers where the customer algorithm can access the data for further processing.
- The transceivers on the slave modules can be individually configured, which microphone channels should be transmitted to the master.
- Sample code and different slave / microphone configurations can be found here [3].

### 4.2 Demo software installed on the AURIX™

The evaluation kit is delivered with a preinstalled software. The following chapter describes the functions of the demo software.

Note: The configuration might vary, depending on the order placed.

## 4.2.1 Realtime audio loop back

The system is configured to read the audio data from 8 microphones from 2 slave modules connected.

On the headphone-output one can hear a stereo-mix of all 8 microphone-channels in real-time.

Note: If more than two slaves are connected, only the first two slaves in the daisy chain will be active.

### 4.2.2 Live level meter

The LED ring of the microphone extension board are set up as a live level meter of the 8 different microphone channels.

- The three status LED's are showing in binary-count, which microphone-channel is selected to show the livelevel in the LED ring. See Figure 7.
- The channel selection can be changed by pushing the Button 1 on the AURIX™ board. See Figure 5.
- The LEDs are having a level-distance of 3dB.

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# 5 System design

### 5.1 A<sup>2</sup>B master PCB

## **5.1.1** Schematics

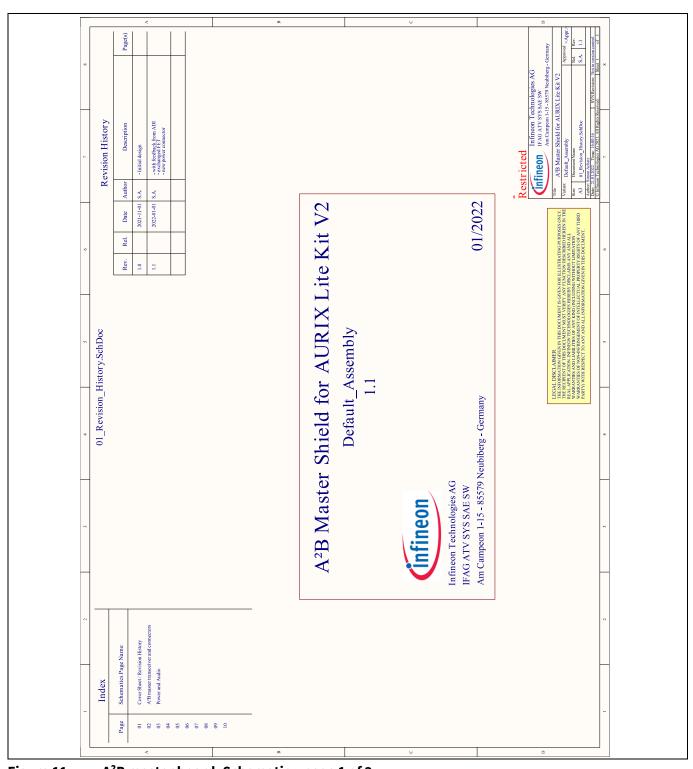


Figure 11 A<sup>2</sup>B master board: Schematic – page 1 of 3

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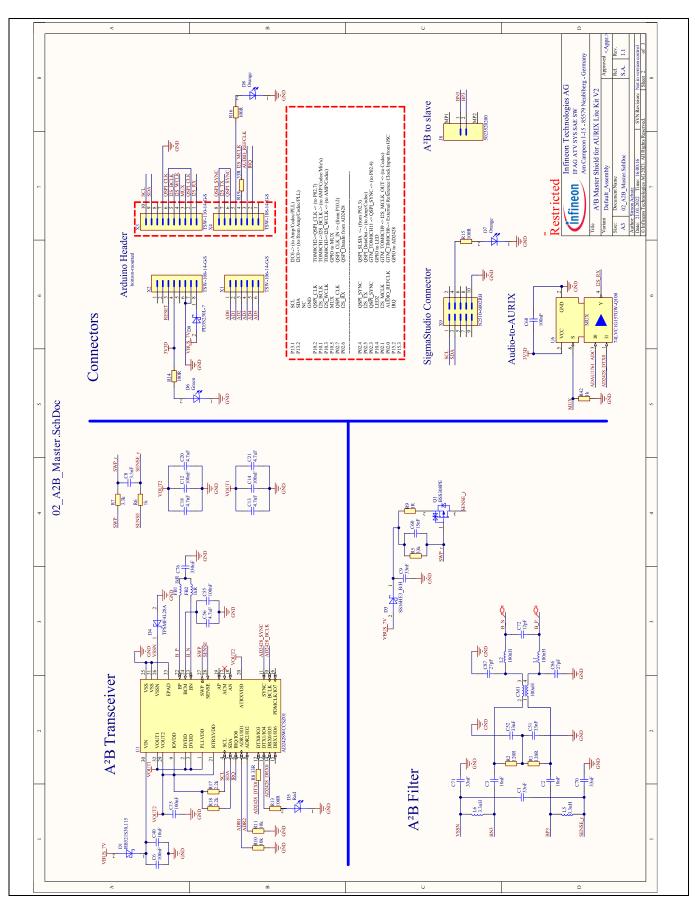


Figure 12 A<sup>2</sup>B master board: Schematic – page 2 of 3

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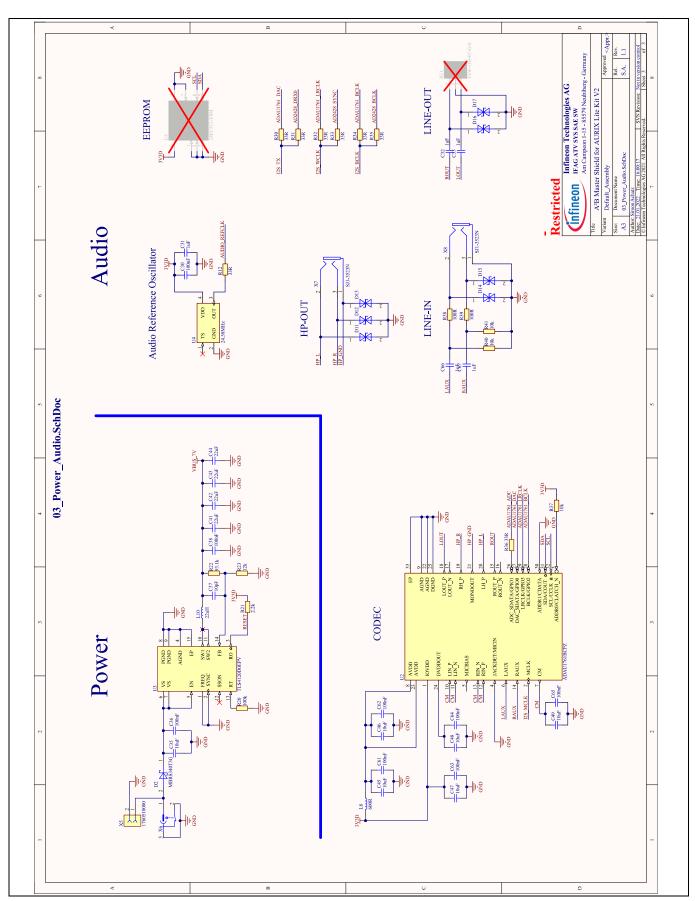


Figure 13 A<sup>2</sup>B master board: Schematic - page 3 of 3

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## 5.1.2 Placement

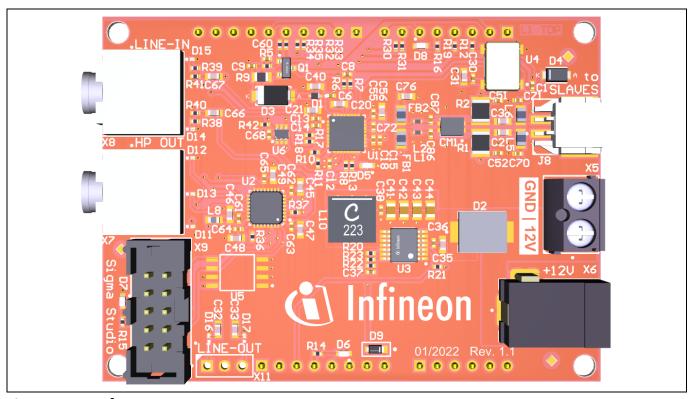


Figure 14 A<sup>2</sup>B master board: Component placement TOP

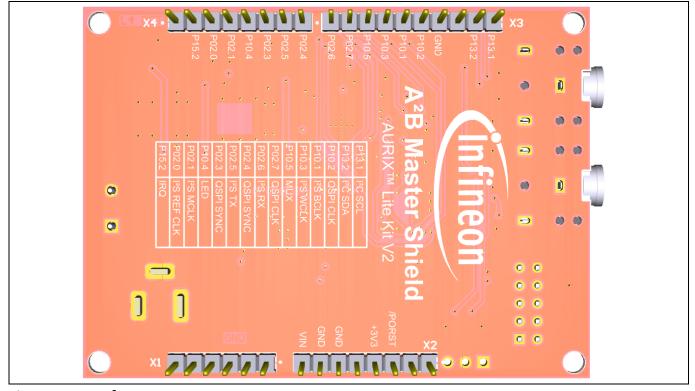


Figure 15 A<sup>2</sup>B master board: Component placement BOTTOM

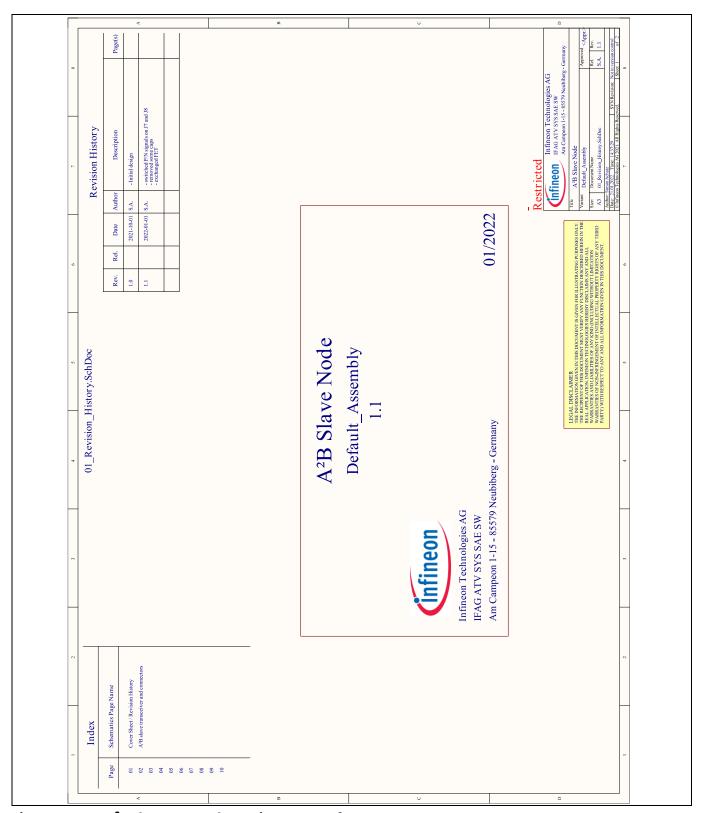
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## 5.2 Microphone slave PCB

### 5.2.1 Schematics



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Figure 16 A<sup>2</sup>B slave PCB: Schematic – page 1 of 2

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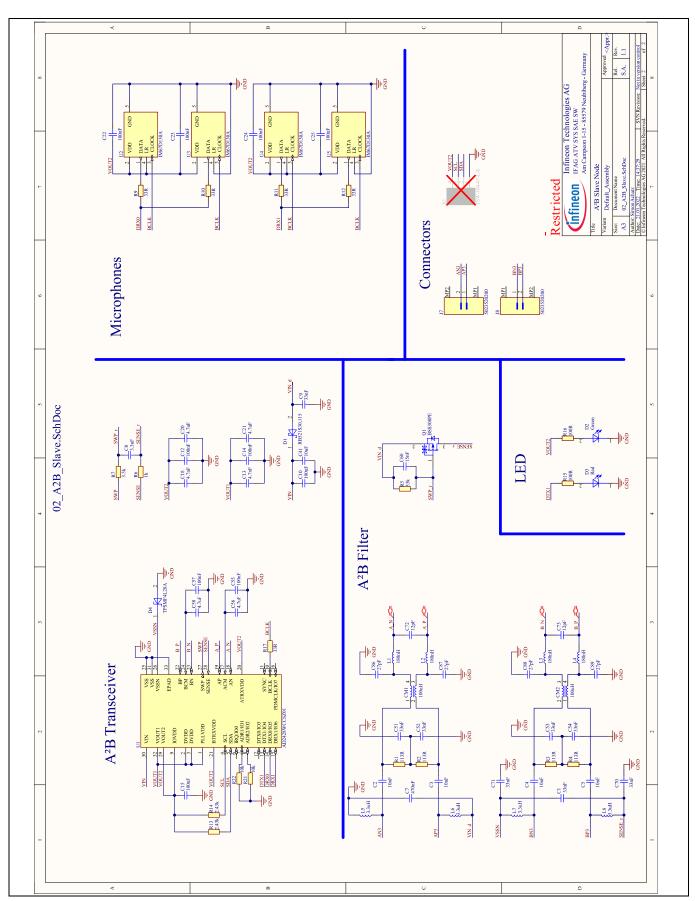


Figure 17 A<sup>2</sup>B slave PCB: Schematic - page 2 of 2

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## 5.2.2 Placement

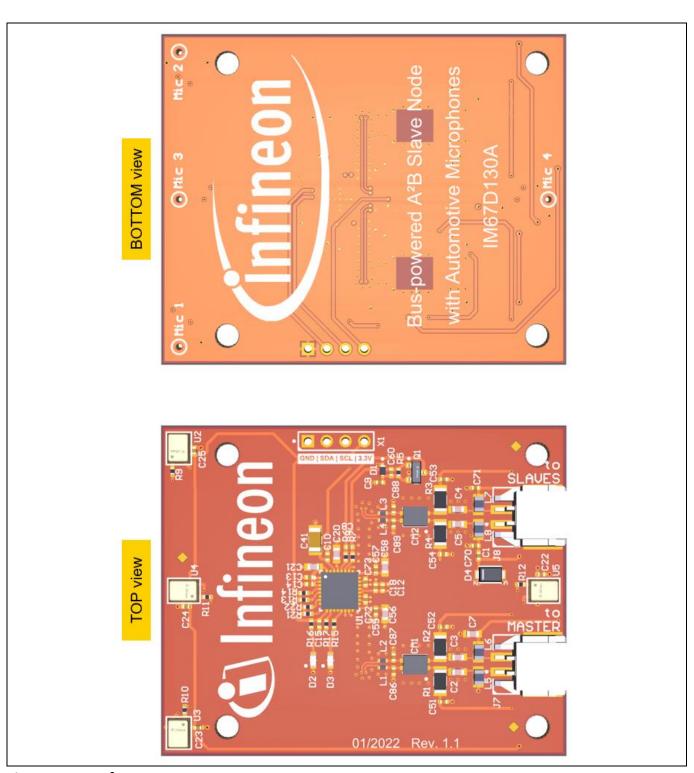


Figure 18 A<sup>2</sup>B slave PCB: Component placement TOP and BOTTOM

## **Evaluation kit to experiment with different system configurations of XENSIV**



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## 5.3 Microphone array extension PCB

### 5.3.1 Schematics

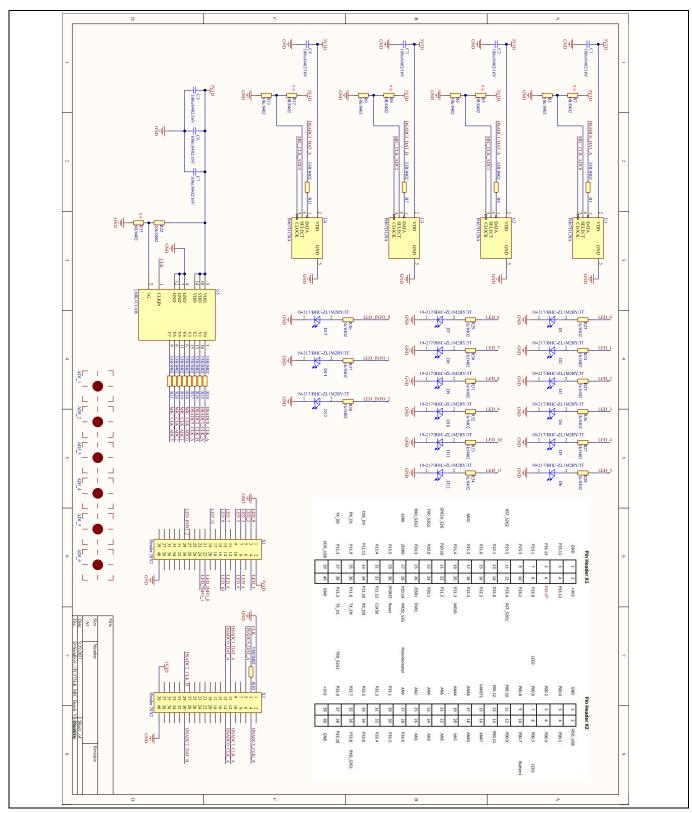


Figure 19 Microphone array extension board: Schematic - page 1 of 1

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## 5.3.2 Placement

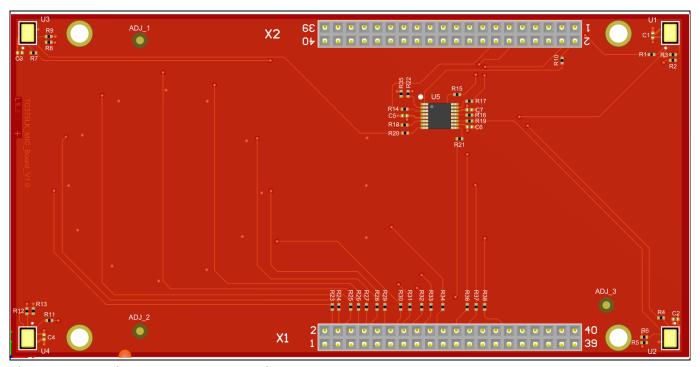


Figure 20 Microphone array extension board: Component placement TOP

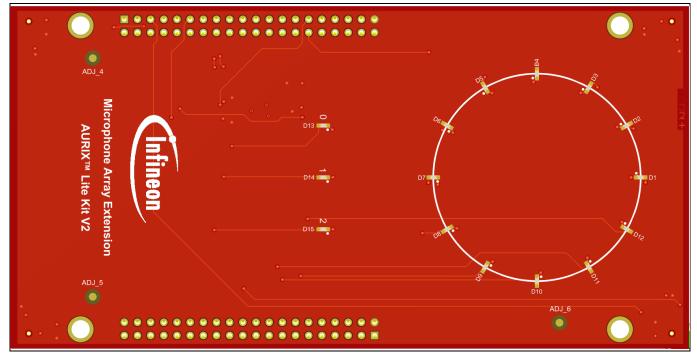


Figure 21 Microphone array extension board: Component placement BOTTOM

## Infineon A<sup>2</sup>B evaluation kit

## **Evaluation kit to experiment with different system configurations of XENSIV**



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# 6 Appendices

# 6.1 Abbreviations and glossary

### Table 3 Abbreviations

Abbreviation	Meaning
μC	Microcontroller
A <sup>2</sup> B	Automotive Audio Bus interface from Analog Devices
ANC	Active noise cancellation
AURIX™	Automotive microcontroller family from Infineon
GPIO	General purpose input / output
IM67D130A	Automotive qualified MEMS microphone from Infineon
LDO	Low drop-out voltage regulator
LED	Light-emitting diode
Master	Main A <sup>2</sup> B transceiver with interface to the microcontroller
MEMS	Micro-electro-mechanical-system
Slave	A <sup>2</sup> B transceiver controlled by the master transceiver
SPL	Sound pressure level
TC375	Microcontroller from the AURIX™ family
TDM	Time-division-multiplex

References

## Infineon A<sup>2</sup>B evaluation kit



# ${\bf Evaluation\ kit\ to\ experiment\ with\ different\ system\ configurations\ of\ XENSIV}$

### References

- [1] Infineon Technologies AG; AURIX™ lite kit V2, Board User's Manual, Revision 2.1; https://www.infineon.com/cms/en/product/evaluation-boards/kit\_a2g\_tc375\_lite/
- [2] Infineon Technologies AG; Audio Application Kit; Kit User's Manual; https://www.infineon.com/cms/en/product/evaluation-boards/kit\_a2g\_tc375\_lite/
- [3] Infineon Technologies AG; AURIX™ code library on GitHub; https://github.com/Infineon/Aurix AudioAppKit
- [4] Infineon Technologies AG; IM67D130A datasheet; <u>https://www.infineon.com/cms/de/product/sensor/mems-microphones/mems-microphones-for-automotive/</u>
- [5] Analog Devices; SigmaStudio® Graphical development tool; <a href="https://www.analog.com/en/design-center/evaluation-hardware-and-software/software/software/software-overview">https://www.analog.com/en/design-center/evaluation-hardware-and-software/software/software/software-overview</a>

# Infineon A<sup>2</sup>B evaluation kit Evaluation kit to experiment with different system configurations of XENSIV Revision history



# **Revision history**

Document revision	Date	Description of changes
Rev. 1.00	2022-02-21	First released version

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